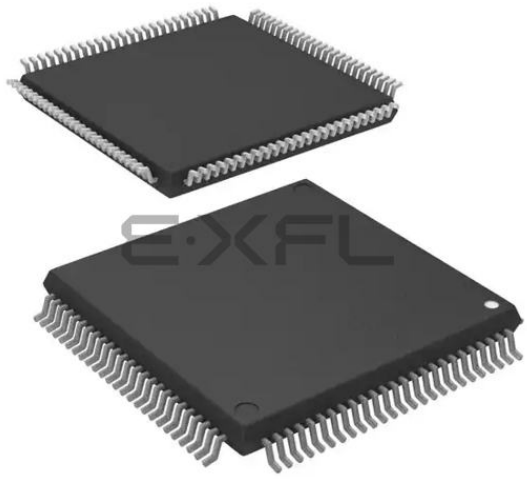
Renesas Electronics America Inc - R5F363A6DFB#U0 Datasheet



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Details	
Product Status	Obsolete
Core Processor	-
Core Size	-
Speed	-
Connectivity	-
Peripherals	-
Number of I/O	-
Program Memory Size	-
Program Memory Type	-
EEPROM Size	-
RAM Size	-
Voltage - Supply (Vcc/Vdd)	-
Data Converters	-
Oscillator Type	-
Operating Temperature	-
Mounting Type	-
Package / Case	-
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f363a6dfb-u0

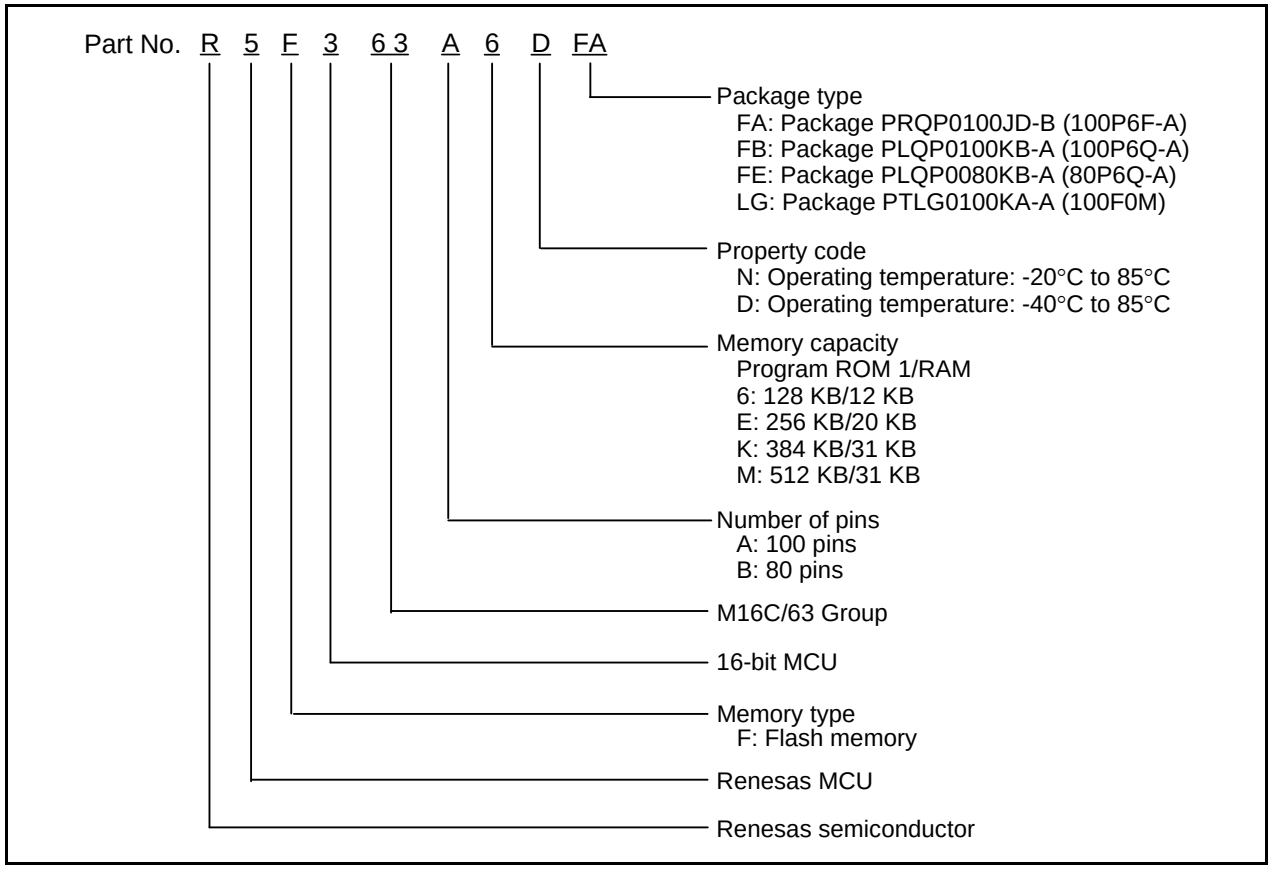


Figure 1.1 Part No., with Memory Size and Package

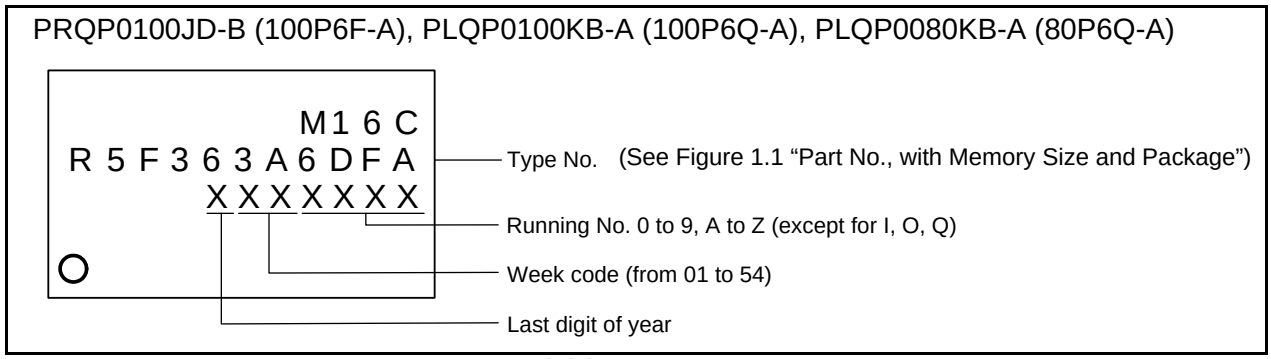


Figure 1.2 Marking Diagram (Top View) (1/2)

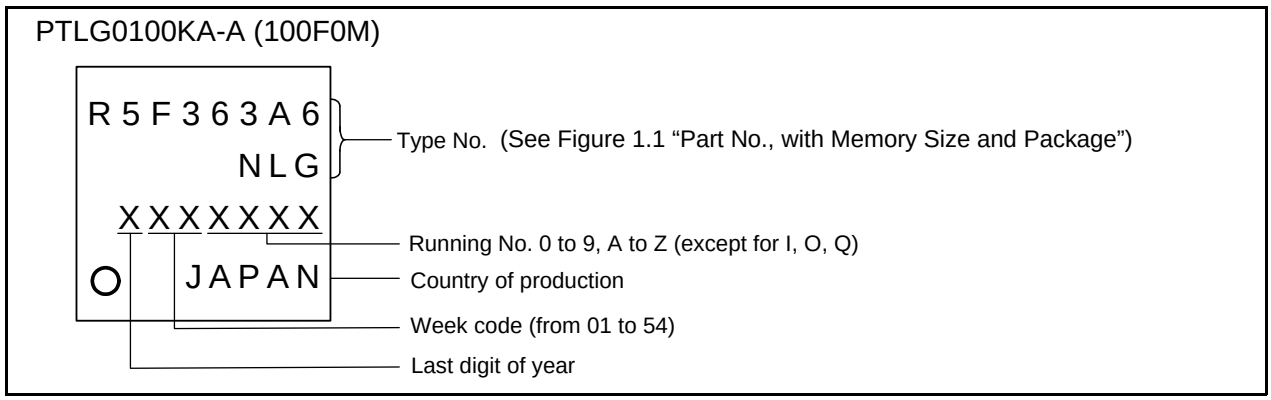
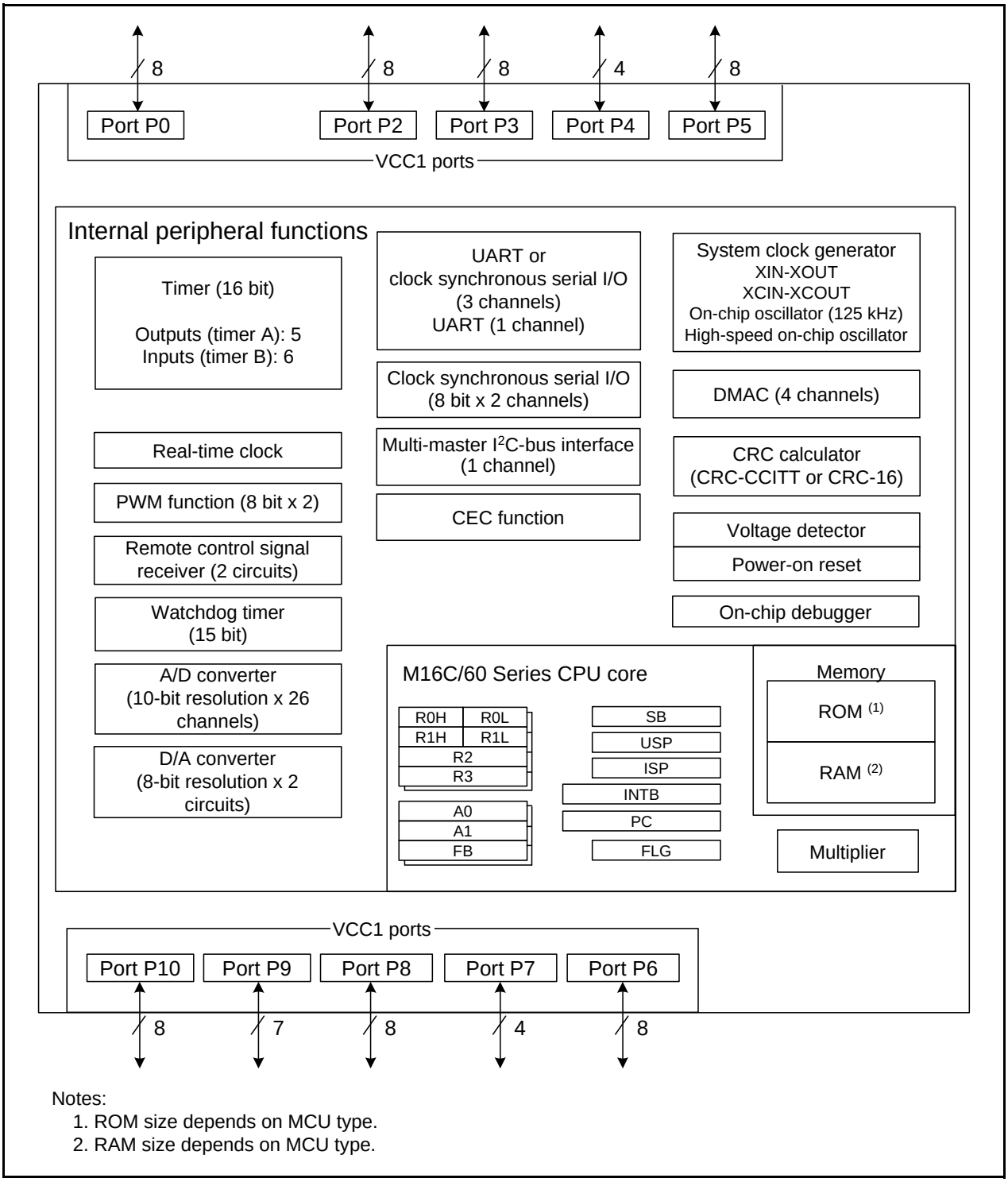


Figure 1.3 Marking Diagram (Top View) (2/2)



Notes:
1. ROM size depends on MCU type.
2. RAM size depends on MCU type.

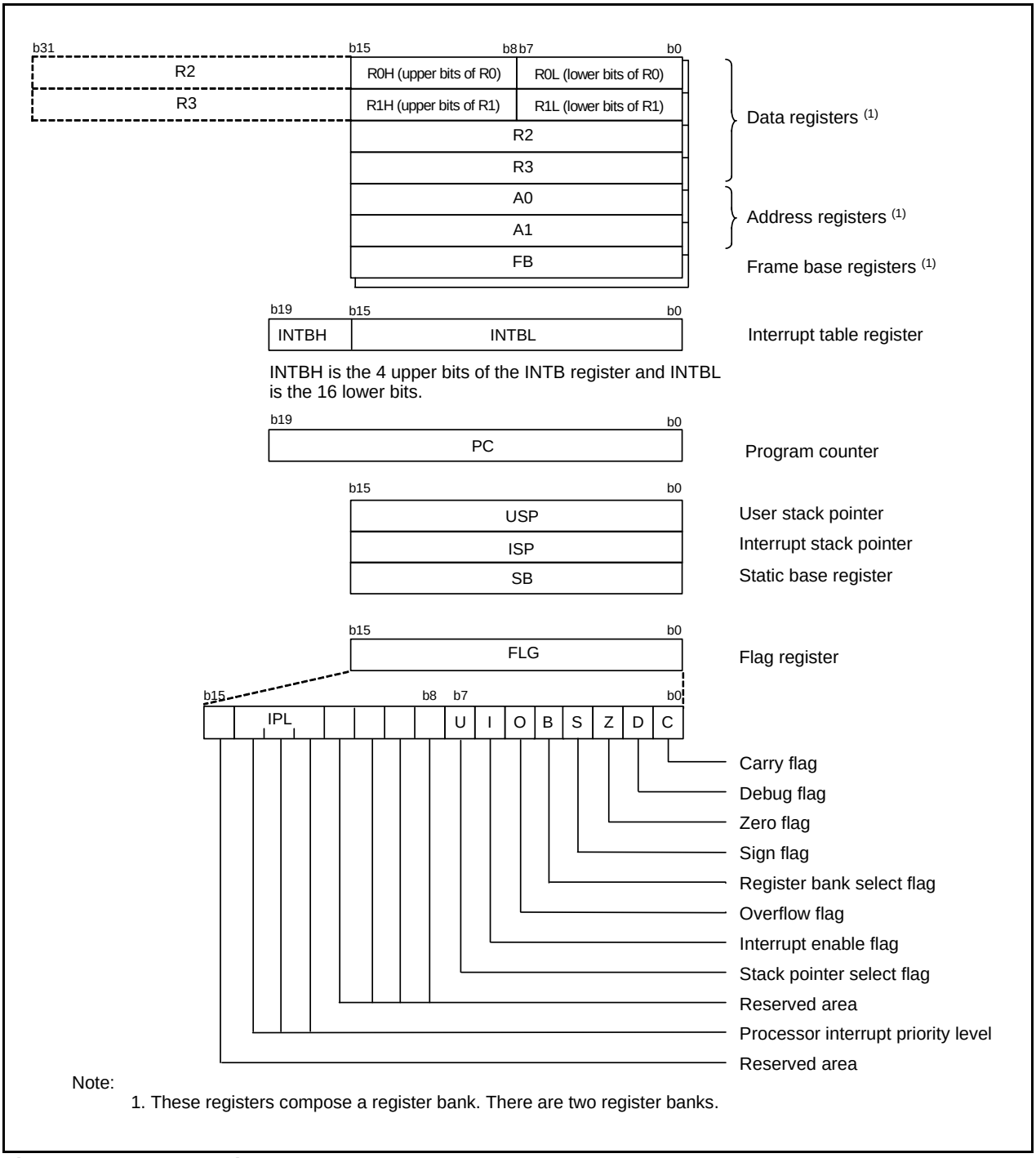
Figure 1.5 Block Diagram for the 80-Pin Package

Table 1.8 Pin Names for the 80-Pin Package (1/2)

Pin No.	Control Pin	Port	I/O Pin for Peripheral Function			
			Interrupt	Timer	Serial interface	A/D converter, D/A converter
1		P9_5			CLK4	ANEX0
2		P9_4		TB4IN/PWM1		DA1
3		P9_3		TB3IN/PWM0		DA0
4		P9_2		TB2IN/PMC0	SOUT3	
5		P9_0		TB0IN	CLK3	
6	CNVSS					
7	XCIN	P8_7				
8	XCOUT	P8_6				
9	$\overline{\text{RESET}}$					
10	XOUT					
11	VSS					
12	XIN					
13	VCC1					
14		P8_5	$\overline{\text{NMI}}$		CEC	
15		P8_4	$\overline{\text{INT2}}$	ZP		
16		P8_3	$\overline{\text{INT1}}$			
17		P8_2	$\overline{\text{INT0}}$			
18		P8_1		TA4IN	$\overline{\text{CTS5}}$/$\overline{\text{RTS5}}$	
19		P8_0		TA4OUT	RXD5/SCL5	
20		P7_7		TA3IN	CLK5	
21		P7_6		TA3OUT	TXD5/SDA5	
22		P7_1		TA0IN/TB5IN	RXD2/SCL2/SCLMM	
23		P7_0		TA0OUT	TXD2/SDA2/SDAMM	
24		P6_7			TXD1/SDA1	
25		P6_6			RXD1/SCL1	
26		P6_5			CLK1	
27		P6_4			$\overline{\text{CTS1}}$/$\overline{\text{RTS1}}$/$\overline{\text{CTS0}}$/ CLKS1	
28		P6_3			TXD0/SDA0	
29		P6_2			RXD0/SCL0	
30		P6_1			CLK0	
31		P6_0		TRHO	$\overline{\text{CTS0}}$/$\overline{\text{RTS0}}$	
32	CLKOUT	P5_7				
33		P5_6				
34		P5_5				
35		P5_4				
36		P5_3				
37		P5_2				
38		P5_1				
39		P5_0				
40		P4_3				

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU registers. Seven registers (R0, R1, R2, R3, A0, A1, and FB) out of 13 compose a register bank, and there are two register banks.



Note:
1. These registers compose a register bank. There are two register banks.

Figure 2.1 CPU Registers

2.8.7 Interrupt Enable Flag (I Flag)

The I flag enables maskable interrupts.
Maskable interrupts are disabled when the I flag is 0, and enabled when it is 1. The I flag becomes 0 when an interrupt request is accepted.

2.8.8 Stack Pointer Select Flag (U Flag)

ISP is selected when the U flag is 0. USP is selected when the U flag is 1.
The U flag becomes 0 when a hardware interrupt request is accepted, or the INT instruction of software interrupt number 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from 0 to 7.
If a requested interrupt has higher priority than IPL, the interrupt request is enabled.

2.8.10 Reserved Areas

Only set these bits to 0. The read value is undefined.

4. Special Function Registers (SFRs)

4.1 SFRs

An SFR is a control register for a peripheral function.

Table 4.1 SFR Information (1) (1)

Address	Register	Symbol	Reset Value
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	0000 0000b (CNVSS pin is low) 0000 0011b (CNVSS pin is high) (2)
0005h	Processor Mode Register 1	PM1	0000 1000b
0006h	System Clock Control Register 0	CM0	0100 1000b
0007h	System Clock Control Register 1	CM1	0010 0000b
0008h	Chip Select Control Register	CSR	01h
0009h	External Area Recovery Cycle Control Register	EWR	XXXX XX00b
000Ah	Protect Register	PRCR	00h
000Bh	Data Bank Register	DBR	00h
000Ch	Oscillation Stop Detection Register	CM2	0X00 0010b (3)
000Dh			
000Eh			
000Fh			
0010h	Program 2 Area Control Register	PRG2C	XXXX XX00b
0011h	External Area Wait Control Expansion Register	EWC	00h
0012h	Peripheral Clock Select Register	PCLKR	0000 0011b
0013h	Sub Clock Division Control Register	SCM0	XXXX X000b
0014h			
0015h	Clock Prescaler Reset Flag	CPSRF	0XXX XXXXb
0016h	Peripheral Clock Stop Register 1	PCLKSTP1	X000 0000b
0017h			
0018h	Reset Source Determine Register	RSTFR	XX00 001Xb (hardware reset) (4)
0019h	Voltage Detector 2 Flag Register	VCR1	0000 1000b (5)
001Ah	Voltage Detector Operation Enable Register	VCR2	00h (5)
001Bh	Chip Select Expansion Control Register	CSE	00h
001Ch			
001Dh			
001Eh	Processor Mode Register 2	PM2	XX00 0X01b
001Fh			

X: Undefined

Notes:
1. The blank areas are reserved. No access is allowed.
2. Software reset, watchdog timer reset, oscillator stop detect reset, voltage monitor 1 reset, and voltage monitor 2 reset do not affect the following bits: bits PM01 and PM00 in the PM0 register.
3. Oscillator stop detect reset does not affect bits CM20, CM21, and CM27.
4. The state of bits in the RSTFR register depends on the reset type.
5. This is the reset value after hardware reset. Refer to the explanation of each register for details.

Table 4.9 SFR Information (9) (1)

Address	Register	Symbol	Reset Value
0240h			
0241h			
0242h			
0243h			
0244h	UART0 Special Mode Register 4	U0SMR4	00h
0245h	UART0 Special Mode Register 3	U0SMR3	000X 0X0Xb
0246h	UART0 Special Mode Register 2	U0SMR2	X000 0000b
0247h	UART0 Special Mode Register	U0SMR	X000 0000b
0248h	UART0 Transmit/Receive Mode Register	U0MR	00h
0249h	UART0 Bit Rate Register	U0BRG	XXh
024Ah	UART0 Transmit Buffer Register	U0TB	XXh
024Bh			XXh
024Ch	UART0 Transmit/Receive Control Register 0	U0C0	0000 1000b
024Dh	UART0 Transmit/Receive Control Register 1	U0C1	00XX 0010b
024Eh	UART0 Receive Buffer Register	U0RB	XXh
024Fh			XXh
0250h	UART Transmit/Receive Control Register 2	UCON	X000 0000b
0251h			
0252h	UART Clock Select Register	UCLKSEL0	X0h
0253h			
0254h	UART1 Special Mode Register 4	U1SMR4	00h
0255h	UART1 Special Mode Register 3	U1SMR3	000X 0X0Xb
0256h	UART1 Special Mode Register 2	U1SMR2	X000 0000b
0257h	UART1 Special Mode Register	U1SMR	X000 0000b
0258h	UART1 Transmit/Receive Mode Register	U1MR	00h
0259h	UART1 Bit Rate Register	U1BRG	XXh
025Ah	UART1 Transmit Buffer Register	U1TB	XXh
025Bh			XXh
025Ch	UART1 Transmit/Receive Control Register 0	U1C0	0000 1000b
025Dh	UART1 Transmit/Receive Control Register 1	U1C1	00XX 0010b
025Eh	UART1 Receive Buffer Register	U1RB	XXh
025Fh			XXh
0260h			
0261h			
0262h			
0263h			
0264h	UART2 Special Mode Register 4	U2SMR4	00h
0265h	UART2 Special Mode Register 3	U2SMR3	000X 0X0Xb
0266h	UART2 Special Mode Register 2	U2SMR2	X000 0000b
0267h	UART2 Special Mode Register	U2SMR	X000 0000b
0268h	UART2 Transmit/Receive Mode Register	U2MR	00h
0269h	UART2 Bit Rate Register	U2BRG	XXh
026Ah	UART2 Transmit Buffer Register	U2TB	XXh
026Bh			XXh
026Ch	UART2 Transmit/Receive Control Register 0	U2C0	0000 1000b
026Dh	UART2 Transmit/Receive Control Register 1	U2C1	0000 0010b
026Eh	UART2 Receive Buffer Register	U2RB	XXh
026Fh			XXh

X: Undefined

Note:
1. The blank areas are reserved. No access is allowed.

Table 4.14 SFR Information (14) (1)

Address	Register	Symbol	Reset Value
0360h	Pull-Up Control Register 0	PUR0	00h
0361h	Pull-Up Control Register 1	PUR1	0000 0000b (2) 0000 0010b
0362h	Pull-Up Control Register 2	PUR2	00h
0363h			
0364h			
0365h			
0366h	Port Control Register	PCR	0000 0XX0b
0367h			
0368h			
0369h	NMI/SD Digital Filter Register	NMIDF	XXXX X000b
036Ah			
036Bh			
036Ch			
036Dh			
036Eh			
036Fh			
0370h	PWM Control Register 0	PWMCON0	00h
0371h			
0372h	PWM0 Prescaler	PWMPRE0	00h
0373h	PWM0 Register	PWMREG0	00h
0374h	PWM1 Prescaler	PWMPRE1	00h
0375h	PWM1 Register	PWMREG1	00h
0376h	PWM Control Register 1	PWMCON1	00h
0377h			
0378h			
0379h			
037Ah			
037Bh			
037Ch	Count Source Protection Mode Register	CSPR	00h (3)
037Dh	Watchdog Timer Refresh Register	WDTR	XXh
037Eh	Watchdog Timer Start Register	WDTS	XXh
037Fh	Watchdog Timer Control Register	WDC	00XX XXXXb
0380h to 038Fh			

X: Undefined

Notes:
1. The blank areas are reserved. No access is allowed.
2. Values after hardware reset, power-on reset, or voltage monitor 0 reset are as follows:
 - 00000000b when a low-level signal is input to the CNVSS pin
 - 00000010b when a high-level signal is input to the CNVSS pin
 Values after voltage monitor 1 reset, voltage monitor 2 reset, software reset, watchdog timer reset, or oscillation stop detect reset are as follows:
 - 00000000b when bits PM01 and PM00 in the PM0 register are 00b (single-chip mode).
 - 00000010b when bits PM01 and PM00 in the PM0 register are 01b (memory expansion mode) or 11b (microprocessor mode).
3. When the CSPROINI bit in the OFS1 address is 0, the reset value is 1000 0000b.

5.1.2 Recommended Operating Conditions

Table 5.2 Recommended Operating Conditions (1/4)

V_{CC1} = V_{CC2} = 1.8 to 5.5 V at T_{opr} = -20°C to 85°C/-40°C to 85°C unless otherwise specified.

Symbol	Parameter			Standard			Unit
				Min.	Typ.	Max.	
V_{CC1}	Supply voltage	CEC function is not used ($V_{CC1} \geq V_{CC2}$)		2.7		5.5	V
		CEC function is not used ($V_{CC1} = V_{CC2}$)		1.8		5.5	V
		CEC function is used		2.7		3.63	V
V_{CC2}	Supply voltage		$V_{CC1} \geq 2.7$	2.7		V_{CC1}	V
			$V_{CC1} < 2.7$		V_{CC1}		V
AV_{CC}	Analog supply voltage				V_{CC1}		V
V_{SS}	Supply voltage				0		V
AV_{SS}	Analog supply voltage				0		V
V_{IH}	High input voltage	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7	2.7 V ≤ V_{CC1} ≤ 5.5 V	0.8V_{CC2}		V_{CC2}	V
			1.8 V ≤ V_{CC1} < 2.7 V	0.85V_{CC2}		V_{CC2}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (in single-chip mode)	2.7 V ≤ V_{CC1} ≤ 5.5 V	0.8V_{CC2}		V_{CC2}	V
			1.8 V ≤ V_{CC1} < 2.7 V	0.85V_{CC2}		V_{CC2}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (data input in memory expansion and microprocessor modes)	2.7 V ≤ V_{CC1} ≤ 5.5 V	0.5V_{CC2}		V_{CC2}	V
			1.8 V ≤ V_{CC1} < 2.7 V	0.55V_{CC2}		V_{CC2}	V
		P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, XIN, $\overline{\text{RESET}}$, CNVSS, BYTE	2.7 V ≤ V_{CC1} ≤ 5.5 V	0.8V_{CC1}		V_{CC1}	V
			1.8 V ≤ V_{CC1} < 2.7 V	0.85V_{CC1}		V_{CC1}	V
		P7_0, P7_1, P8_5	2.7 V ≤ V_{CC1} ≤ 5.5 V	0.8V_{CC1}		6.5	V
			1.8 V ≤ V_{CC1} < 2.7 V	0.85V_{CC1}		6.5	V
		CEC		0.7V_{CC1}			V
V_{IL}	Low input voltage	P3_1 to P3_7, P4_0 to P4_7, P5_0 to P5_7		0		0.2V_{CC2}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (in single-chip mode)		0		0.2V_{CC2}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 (data input in memory expansion and microprocessor mode)		0		0.16V_{CC2}	V
		P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7 XIN, $\overline{\text{RESET}}$, CNVSS, BYTE		0		0.2V_{CC1}	V
		CEC				0.26V_{CC1}	V

Table 5.11 Flash Memory (Data Flash) Electrical Characteristics

V_{CC1} = 2.7 to 5.5 V at T_{opr} = -20 to 85°C/-40 to 85°C, unless otherwise specified.

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
-	Program and erase cycles (1), (3), (4)	V_{CC1} = 3.3 V, T_{opr} = 25°C	10,000 (2)			times
-	2 word program time	V_{CC1} = 3.3 V, T_{opr} = 25°C		300	4000	µs
-	Lock bit program time	V_{CC1} = 3.3 V, T_{opr} = 25°C		140	3000	µs
-	Block erase time	V_{CC1} = 3.3 V, T_{opr} = 25°C		0.2	3.0	s
$t_{d(SR-SUS)}$	Time delay from suspend request until suspend				$5 + \frac{3}{f_{(BCLK)}}$	ms
-	Interval from erase start/restart until following suspend request		0			µs
-	Suspend interval necessary for auto-erasure to complete (7)		20			ms
-	Time from suspend until erase restart				$30 + \frac{1}{f_{(BCLK)}}$	µs
-	Program, erase voltage		2.7		5.5	V
-	Read voltage		2.7		5.5	V
-	Program, erase temperature		–20/–40		85	°C
t_{PS}	Flash memory circuit stabilization wait time				50	µs
-	Data hold time (6)	Ambient temperature = 55°C	20			year

Notes:
1. Definition of program and erase cycles
   The program and erase cycles refer to the number of per-block erasures.
   If the program and erase cycles are n (n = 10,000), each block can be erased n times.
   For example, if a 4 KB block is erased after writing 2 word data 1,024 times, each to a different address, this counts as one program and erase cycles. Data cannot be written to the same address more than once without erasing the block (rewrite prohibited).
2. Cycles to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
3. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 256 groups before erasing them all in one operation. In addition, averaging the erasure cycles between blocks A and B can further reduce the actual erasure cycles. It is also advisable to retain data on the erasure cycles of each block and limit the number of erase operations to a certain number.
4. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
5. Customers desiring program/erase failure rate information should contact a Renesas Electronics sales office.
6. The data hold time includes time that the power supply is off or the clock is not supplied.
7. After an erase start or erase restart, if an interval of at least 20 ms is not set before the next suspend request, the erase sequence cannot be completed.

Table 5.14 Voltage Detector 2 Electrical Characteristics

The measurement condition is V_{CC1} = 1.8 to 5.5 V, T_{opr} = -20°C to 85°C/-40°C to 85°C, unless otherwise specified.

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{det2}	Voltage detection level Vdet2_0	When V_{CC1} is falling	3.70	4.00	4.30	V
-	Hysteresis width at the rising of V_{CC1} in voltage detector 2			0.15		V
-	Voltage detector 2 response time (2)	When V_{CC1} falls from 5 V to (Vdet2_0 - 0.1) V			200	µs
-	Voltage detector self power consumption	VC27 = 1, V_{CC1} = 5.0 V		1.7		µA
$t_{d(E-A)}$	Waiting time until voltage detector operation starts (1)				100	µs

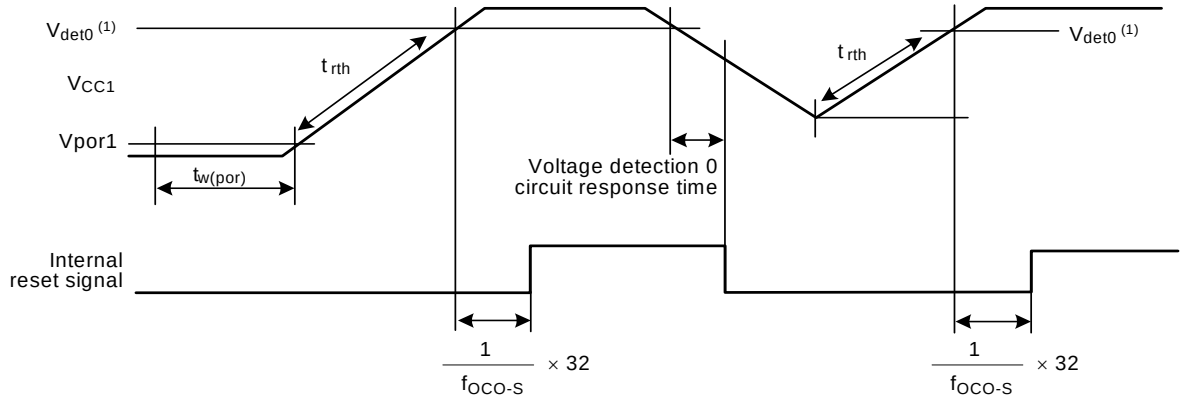
Notes:
1. Necessary time until the voltage detector operates after setting to 1 again after setting the VC27 bit in the VCR2 register to 0.
2. Time from when passing the V_{det2} until when a voltage monitor 2 reset is generated.

Table 5.15 Power-On Reset Circuit

The measurement condition is V_{CC1} = 2.0 to 5.5 V, T_{opr} = -20°C to 85°C/ -40°C to 85°C, unless otherwise specified.

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por1}	Voltage at which power-on reset enabled (1)				0.5	V
t_{rth}	External power V_{CC1} rise gradient		2.0		50000	mV/ms
$t_{w(por)}$	Time necessary to enable power-on reset		300			ms

Note:
1. To use the power-on reset function, enable voltage monitor 0 reset by setting the LVDAS bit in the OFS1 address to 0. Also, set the VDSEL1 bit to 0 (Vdet0_2).



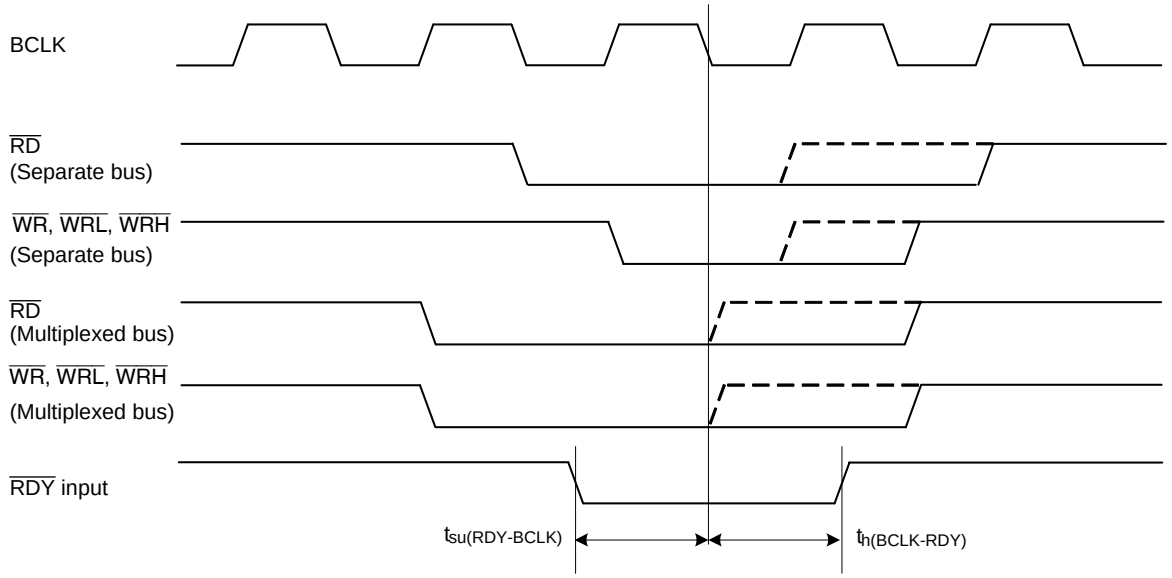
Note:
1. V_{det0} indicates the voltage detection level of the voltage detection 0 circuit.

Figure 5.4 Power-On Reset Circuit Electrical Characteristics

Memory Expansion Mode and Microprocessor Mode

$V_{CC1} = V_{CC2} = 5\ V$

(Effective in wait state setting**)**



Measuring conditions

- $V_{CC1} = V_{CC2} = 5\ V$
- Input timing voltage: $V_{IL} = 1.0\ V$, $V_{IH} = 4.0\ V$
- Output timing voltage: $V_{OL} = 2.5\ V$, $V_{OH} = 2.5\ V$

Figure 5.14 Timing Diagram

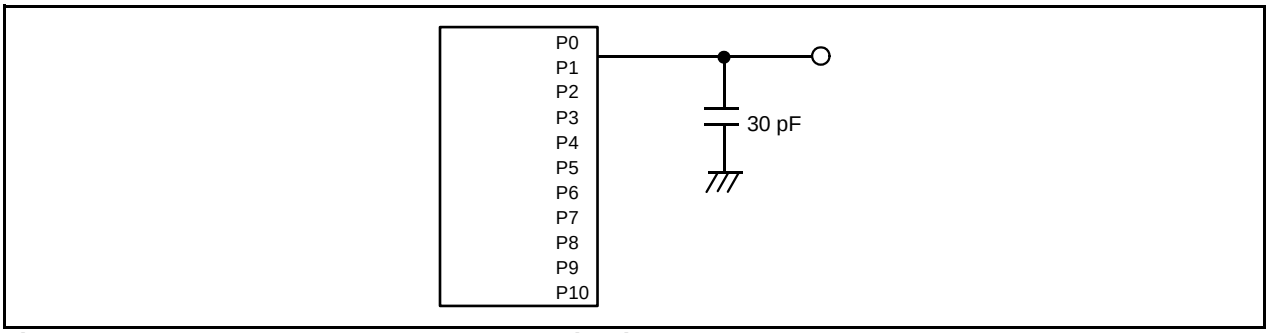
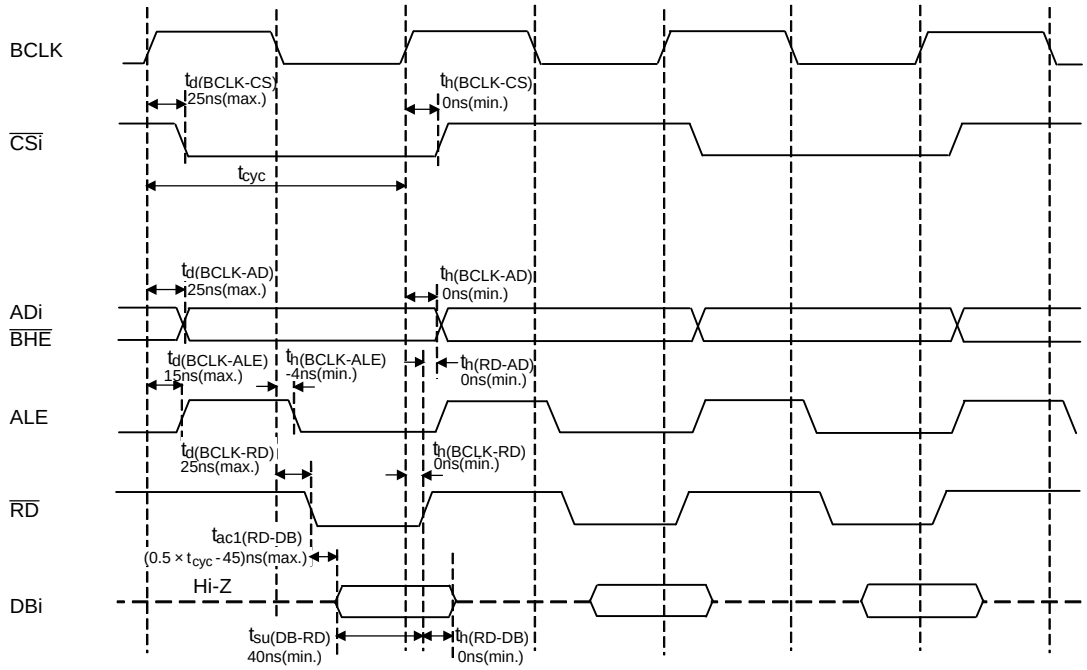


Figure 5.15 Ports P0 to P10 Measurement Circuit

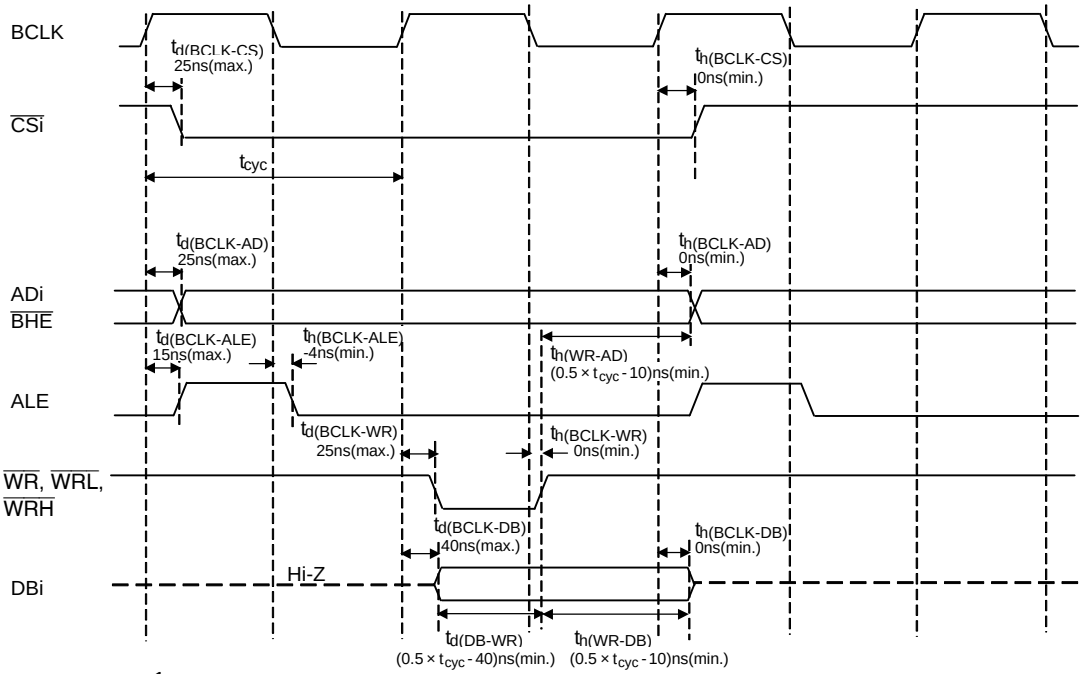
Memory Expansion Mode and Microprocessor Mode
(in no wait state setting)

$V_{CC1} = V_{CC2} = 5V$

Read timing



Write timing



$$t_{cyc} = \frac{1}{f_{(BCLK)}}$$

Measuring conditions

- $V_{CC1} = V_{CC2} = 5V$
- Input timing voltage: $V_{IL} = 0.8$ V, $V_{IH} = 2.0$ V
- Output timing voltage: $V_{OL} = 0.4$ V, $V_{OH} = 2.4$ V

Figure 5.16 Timing Diagram

$V_{CC1} = V_{CC2} = 3\ V$

Switching Characteristics

($V_{CC1} = V_{CC2} = 3$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

5.3.4.4 In Wait State Setting 2φ + 3φ, 2φ + 4φ, 3φ + 4φ, and 4φ + 5φ, and When Accessing External Area

Table 5.60 Memory Expansion and Microprocessor Modes (in Wait State Setting 2φ + 3φ, 2φ + 4φ, 3φ + 4φ, and 4φ + 5φ, and When Accessing External Area)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	See Figure 5.30		30	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		0		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(Note 2)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			30	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		0		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			25	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		-4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			30	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			30	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK) (3)		0		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(Note 1)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) (3)		(Note 2)		ns

Notes:

1. Calculated according to the BCLK frequency as follows:

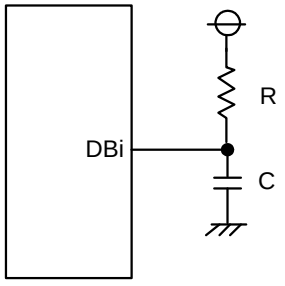
$$\frac{(n-0.5)\times 10^9}{f_{(BCLK)}} - 40[ns]$$

n is 3 for 2φ + 3φ, 4 for 2φ + 4φ, 4 for 3φ + 4φ, and 5 for 4φ + 5φ.

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5\times 10^9}{f_{(BCLK)}} - 10[ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
Hold time of data bus is expressed in
$t = -CR \times \ln(1 - V_{OL}/V_{CC2})$
by a circuit of the right figure.
For example, when $V_{OL} = 0.2V_{CC2}$, C = 30 pF, R = 1 kΩ, hold time of output low level is
$t = -30\ pF \times 1\ k\Omega \times \ln(1 - 0.2V_{CC2}/V_{CC2})$
= 6.7 ns.



$V_{CC1} = V_{CC2} = 1.8\ V$

Timing Requirements

($V_{CC1} = V_{CC2} = 1.8$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

Table 5.71 Timer A Input (Two-Phase Pulse Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	3		µs
$t_{su(TAIN-TAOUT)}$	TAiOUT input setup time	800		ns
$t_{su(TAOUT-TAIN)}$	TAiIN input setup time	800		ns

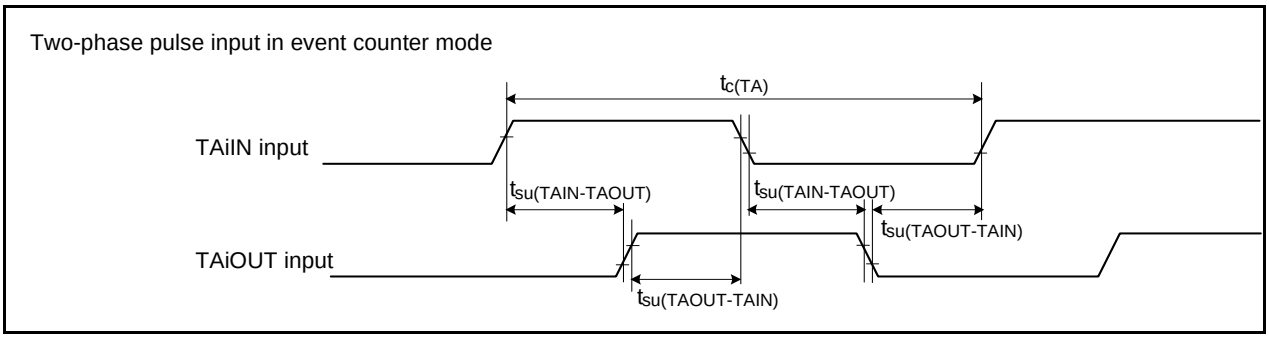


Figure 5.39 Timer A Input (Two-Phase Pulse Input in Event Counter Mode)

$V_{CC1} = V_{CC2} = 1.8\ V$

Timing Requirements

($V_{CC1} = V_{CC2} = 1.8$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

5.4.2.5 Serial Interface

Table 5.75 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	800		ns
$t_{w(CKH)}$	CLKi input high pulse width	400		ns
$t_{w(CKL)}$	CLKi input low pulse width	400		ns
$t_{d(C-Q)}$	TXDi output delay time		240	ns
$t_{h(C-Q)}$	TXDi hold time	0		ns
$t_{su(D-C)}$	RXDi input setup time	200		ns
$t_{h(C-D)}$	RXDi input hold time	90		ns

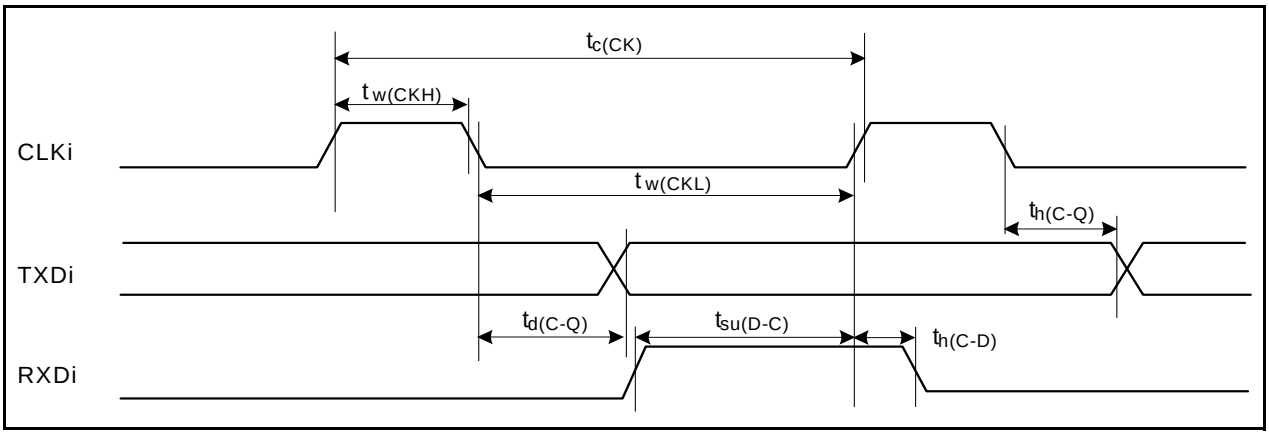


Figure 5.41 Serial Interface

5.4.2.6 External Interrupt $\overline{INTi}$ Input

Table 5.76 External Interrupt $\overline{INTi}$ Input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INTi}$ input high pulse width	1000		ns
$t_{w(INL)}$	$\overline{INTi}$ input low pulse width	1000		ns
tr(INT)	$\overline{INTi}$ input rising time		100	µs
tf(INT)	$\overline{INTi}$ input falling time		100	µs

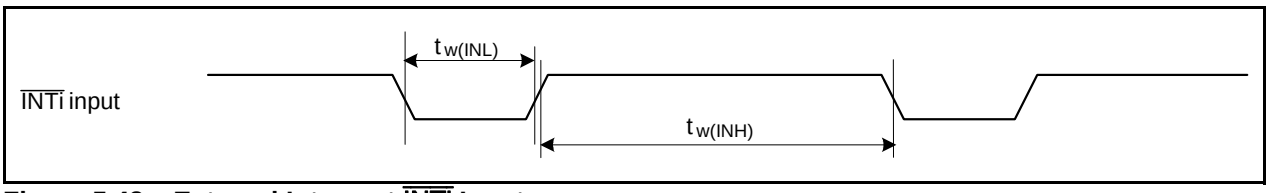
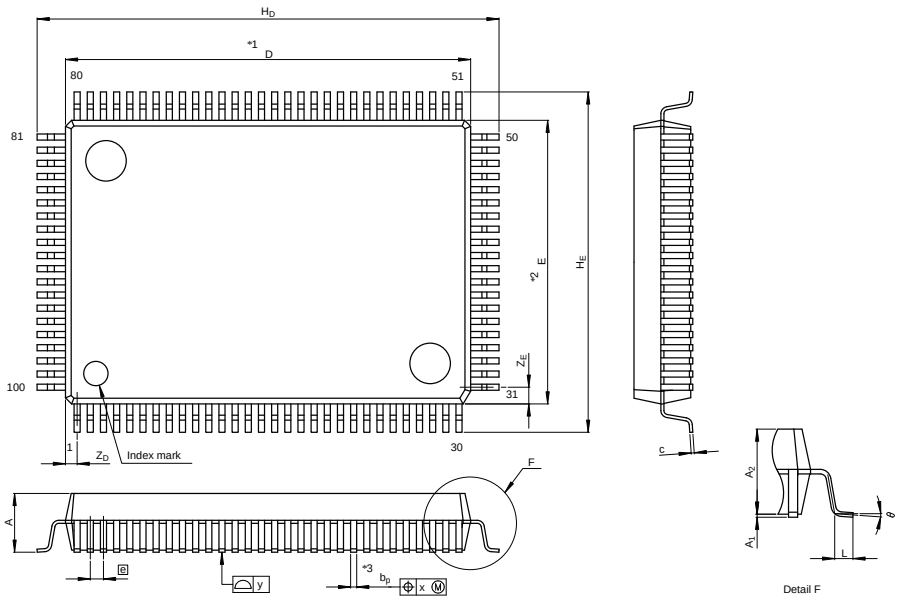


Figure 5.42 External Interrupt $\overline{INTi}$ Input

Appendix 1. Package Dimensions

The information on the latest package dimensions or packaging may be obtained from “Packages“ on the Renesas Electronics website.

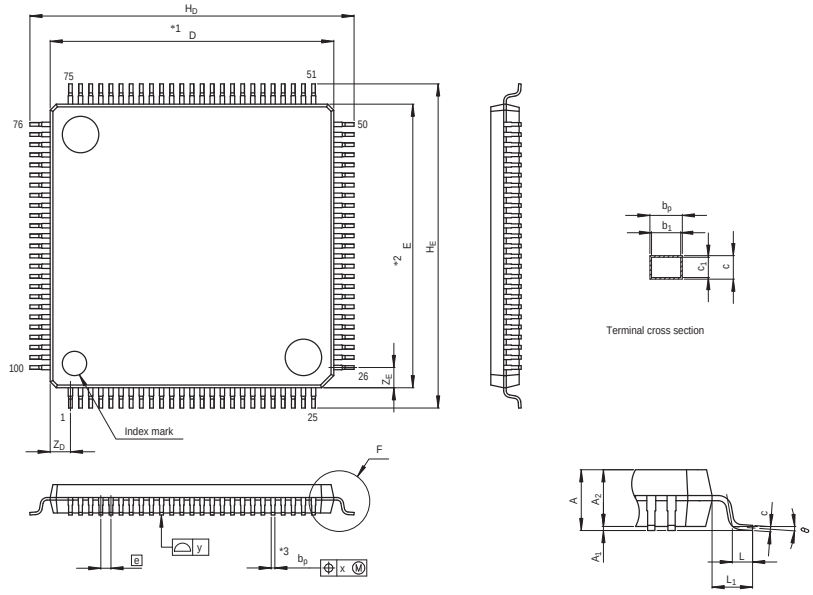
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-QFP100-14x20-0.65	PRQP0100JD-B	100P6F-A	1.8g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	19.8	20.0	20.2
E	13.8	14.0	14.2
A_2	—	2.8	—
H_D	22.5	22.8	23.1
H_E	16.5	16.8	17.1
A	—	—	3.05
A_1	0	0.1	0.2
b_p	0.25	0.3	0.4
c	0.13	0.15	0.2
θ	0°	—	10°
e	—	0.65	—
x	—	—	0.13
y	—	—	0.10
Z_D	—	0.575	—
Z_E	—	0.825	—
L	0.4	0.6	0.8

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP100-14x14-0.50	PLQP0100KB-A	100P6Q-A / FP-100U / FP-100UV	0.6g



NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.15	0.20	0.25
b_1	—	0.18	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.5	—
x	—	—	0.08
y	—	—	0.08
Z_D	—	1.0	—
Z_E	—	1.0	—
L	0.35	0.5	0.65
L_1	—	1.0	—

REVISION HISTORY	M16C/63 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.30	Jul 15, 2009	-	First Edition issued.
0.40	Aug 18, 2009	3	Table 1.2 “Specifications for the 100-Pin Package (2/2)” partially modified
		6	Table 1.5 “Product List” partially modified
		7	Figure 1.1 “Part No., with Memory Size and Package” partially modified
		12	Figure 1.7 “Pin Assignment for the 100-Pin Package” added
		13	Table 1.6 “Pin Names for the 100-Pin Package (1/2)” partially modified
		14	Table 1.7 “Pin Names for the 100-Pin Package (2/2)” partially modified
		107	Table 5.65 “External Clock Input (XIN Input)” partially modified
		112	Appendix 1. “Package Dimensions” PTLG0100KA-A added
0.41	Aug 25, 2009	6	Table 1.5 “Product List” Part No. partially modified
		7	Figure 1.3 “Marking Diagram (Top View) (2/2)” added
1.00	Sep 15, 2009	52	Table 5.6 “A/D Conversion Characteristics (1/2)” note 3 added
2.00	Feb 07, 2011	Overall	001Ah Voltage Detector Operation Enable Register: Changed reset value from “000X 0000b”.
		Overall	002Ah Voltage Monitor 0 Control Register: Changed reset value from “1100 XX10b”.
		Overall	002Bh Voltage Monitor 1 Control Register: Changed reset value from “1000 1X10b”.
		Overall	0324h Increment/Decrement Flag: Changed name from Up/Down Flag.
		Overall	03DCh D/A Control Register: Changed reset value from “XXXX XX00b”.
		Overall	D08Ah to D08Bh PMC0 Counter Value Register: Deleted.
		Overall	D09Eh to D09Fh PMC1 Counter Value Register: Deleted.
		Overview	
		3, 5	Table 1.2 and Table 1.4 Specifications for the 100/80-Pin Package: Deleted note 1.
		6	Table 1.5 Product List: Changed the development status.
		18	Table 1.10 Pin Functions for the 100-Pin Package (1/3): Changed the descriptions of the $\overline{\text{HOLD}}$ pin.
		Address Space	
		27	Figure 3.2 Memory Map: Added note 1 and 3 to the reserved areas.
		Special Function Registers (SFRs)	
		29	Table 4.1 SFR Information (1): • Deleted “the VCR1 register, the VCR2 register” from note 2. • Deleted notes 5 to 6 and added note 5.
		30	Table 4.2 SFR Information (2): Deleted notes 2 to 7 and added note 2.
		47	4.2.1 Register Settings: Added the description regarding read-modify-write instructions.
		48	Table 4.20 Read-Modify-Write Instructions: Added.
		Electrical Characteristics	
		49	Table 5.1 Absolute Maximum Ratings: Divide a row for T_{opr} (Flash program erase) into Program area and Data area.
		50	Table 5.2 Recommended Operating Conditions (1/4): Added rows for the CEC value to V_{CC1}, V_{IH}, and V_{IL}.
		56	Table 5.9 CPU Clock When Operating Flash Memory ($f_{(BCLK)}$): Added note 3.
		56	Table 5.10 Flash Memory (Program ROM 1, 2) Electrical Characteristics: Added a condition to the Read voltage row.
		59	Table 5.15 Power-On Reset Circuit: • Changed the maximum value for V_{por1} from 0.1. • Added the $t_{w(por)}$ row. • Added the last line in note 1.
		59	Figure 5.4 Power-On Reset Circuit Electrical Characteristics: Deleted note 2.
		61	Table 5.17 40 MHz On-Chip Oscillator Electrical Characteristics: Deleted note 1.
		63	Table 5.20 Electrical Characteristics (2): Added “ZP, IDU, IDV, IDW” to the V_{T+} - V_{T-} row.
		70, 91, 113	5.2.2.7, 5.3.2.7, and 5.4.2.7 Multi-master I^2C-bus: Added.
		71	Table 5.35 Memory Expansion Mode and Microprocessor Mode: Changed $\overline{\text{RDY}}$ input setup time from 30.

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

1. Handling of Unused Pins

   Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

   — The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.